

### Features

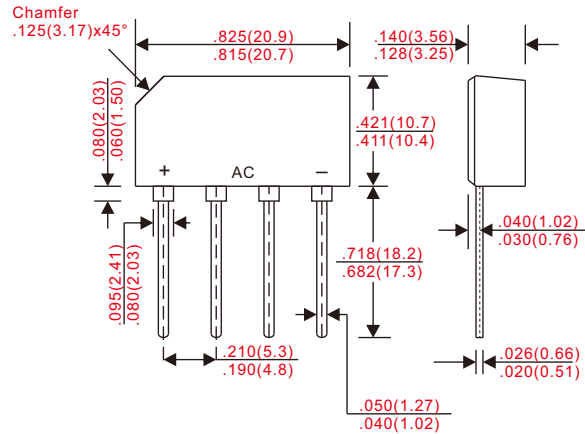
- Recommended for non-automatic applications.
- Ideal for & save space on printed circuit board.
- Applicable for automatic insertion.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Glass passivated chip junctions.
- Suffix "G" indicates Halogen-free part, ex. GBL4005G.
- Lead-free parts meet RoHS requirements.

### Mechanical data

- Epoxy: UL94V-0 rated flame retardant
- Case : Molded plastic, GBL
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Weight : Approximated 2.0 gram

### Outline

GBL



Dimensions in inches and (millimeters)

### Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol		UNIT
Maximum Average Forward Rectified Output Current @T <sub>A</sub> = 25°C		I <sub>O</sub>	2	A
Forward Surge Current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I <sub>FSM</sub>	80	A
Rating for fusing (t<8.3ms)		I <sup>2</sup> t	27	A <sup>2</sup> sec
Storage temperature Range		T <sub>STG</sub>	-55 ~ +150	°C
Typical thermal resistance per leg		R <sub>θJA</sub>	40	°C/W
		R <sub>θJC</sub>	12	
Maximum Reverse Current @T <sub>A</sub> = 25°C at Rated D.C Blocking Voltage @T <sub>A</sub> = 125°C		I <sub>R</sub>	5 300	uA

Symbol	Marking code	Max. repetitive peak reverse voltage V <sub>RRM</sub> (V)	Max. RMS voltage V <sub>RMS</sub> (V)	Max. DC blocking voltage V <sub>R</sub> (V)	Max. forward voltage @2A, T <sub>A</sub> = 25°C V <sub>F</sub> (V)	Operating Junction temperature T <sub>J</sub> (°C)
GBL202	GBL22	200	140	200	1.1	-55 ~ +150
GBL206	GBL26	600	420	600		
GBL208	GBL28	800	560	800		

Rating and characteristic curves

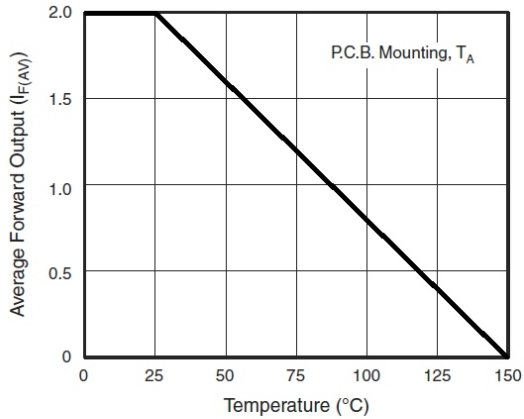


Fig. 1 - Derating Curve Output Rectified Current

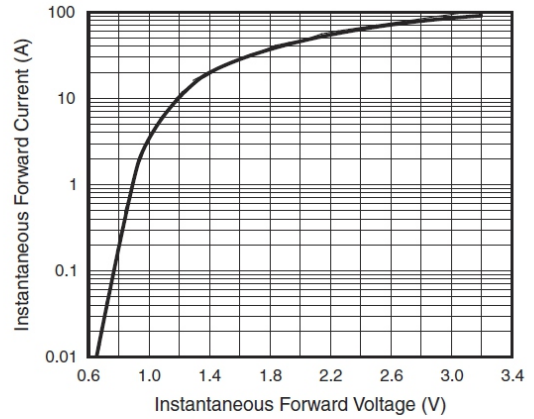


Fig. 3 - Typical Forward Characteristics Per Diode

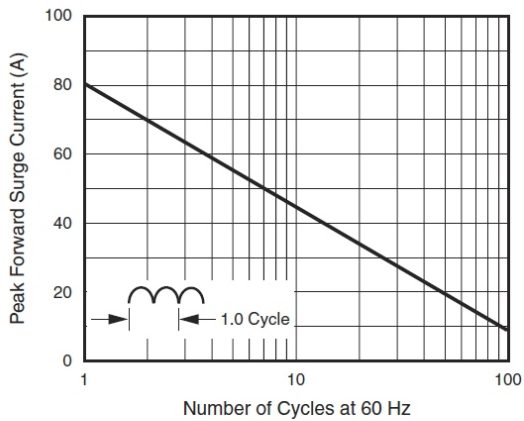


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current Per Diode

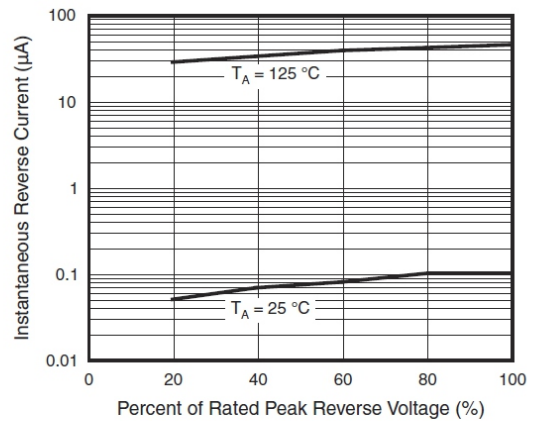


Fig. 4 - Typical Reverse Characteristics Per Diode

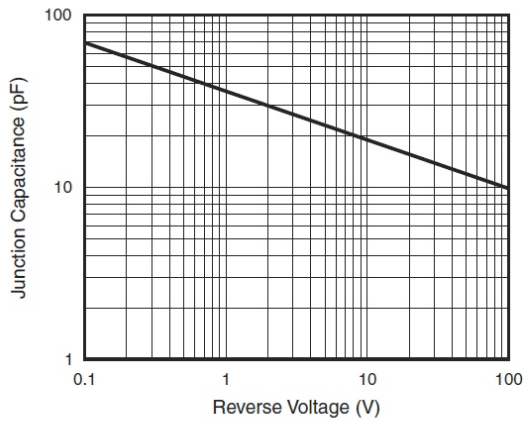


Fig. 5 - Typical Junction Capacitance Per Diode

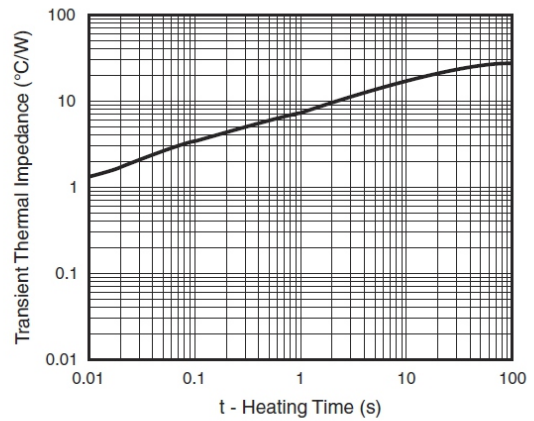


Fig. 6 - Typical Transient Thermal Impedance

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